

67,200-261  
Serial Number 09/821,521

## AMENDMENTS

### *In the Claims*

Please amend claim 9 and claim 15 as follows.

9. (twice amended) A microelectronic fabrication comprising:

a substrate; and

B 1  
a spirally patterned conductor layer formed over the substrate, wherein the spirally patterned conductor layer terminates in a microelectronic structure formed within the center of the spirally patterned conductor layer, wherein the spirally patterned conductor layer forms a planar spiral inductor, and wherein the microelectronic structure formed within the center of the spirally patterned conductor layer comprises a series of at least four electrically interconnected sub-patterns.

15. (amended) A microelectronic fabrication comprising:

a substrate;

B 2  
cont  
a spirally patterned conductor layer formed over the substrate, wherein the spirally patterned conductor layer terminates in a microelectronic structure formed within the center of the spirally patterned conductor layer, wherein the spirally patterned conductor layer forms a planar spiral inductor, and wherein the microelectronic structure formed within the center of the spirally patterned conductor layer comprises a series of electrically interconnected sub-patterns;  
and

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B2  
cancel

a bond wire bonded upon the microelectronic structure, wherein the bond wire has incorporated therein a minimum of one loop.

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✓

Please cancel claim 10.

✓

Please add new claim 16 as follows.

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16. (newly added) A microelectronic fabrication comprising:

a substrate; and

B3

a spirally patterned conductor layer formed over the substrate, wherein the spirally patterned conductor layer terminates in a microelectronic structure formed within the center of the spirally patterned conductor layer, wherein the spirally patterned conductor layer forms a planar spiral inductor, and wherein the microelectronic structure formed within the center of the spirally patterned conductor layer comprises a series of at least four electrically interconnected sub-patterns, such as to attenuate eddy currents within the microelectronic structure.

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### REMARKS

Favorable reconsideration of this application in light of the above amendments and the following remarks is respectfully requested.

Claims 9 and 11-16 are pending in this application. Claims 9 and 15 are amended herein. Claim 10 is canceled herein. Claim 16 is newly added herein. No claims have been allowed.